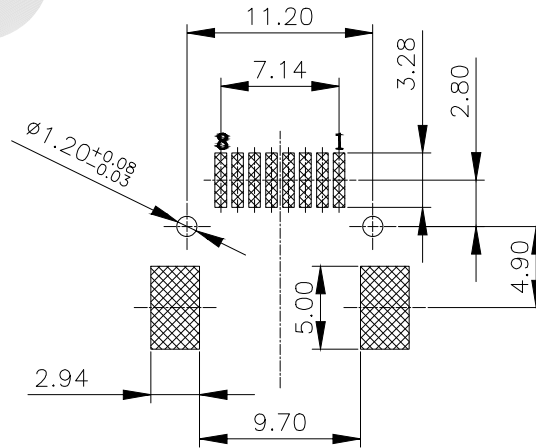
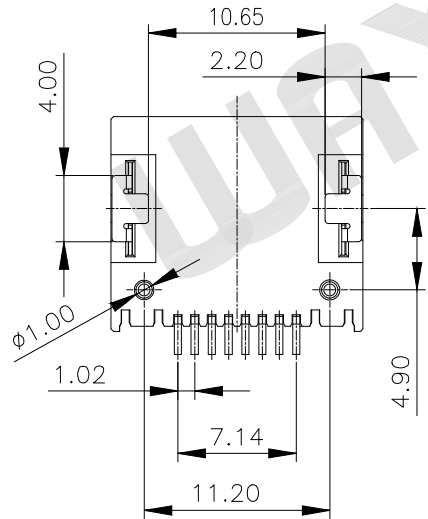
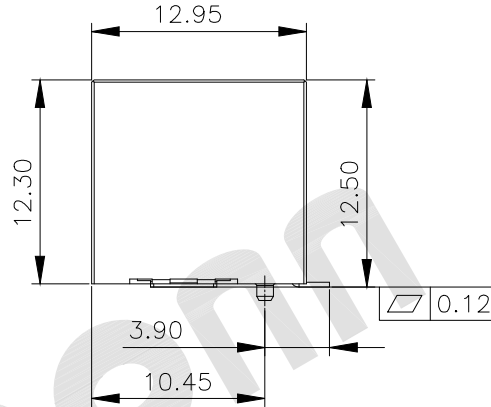
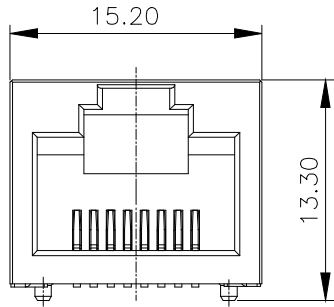


REV.	DESCRIPTION	DRAWN	CHECKED	APPROVED
A	NEW RELEASE	JLZ 03/24/16'	~	



**Description:**

Unshielded 8P8C RJ45 SMT Modular Jack

**Material:**

Housing Material: High Temp Nylon, LCP, UL94V-0  
 Contact Material: Phosphor Bronze T-0.35mm Thickness  
 Plating: Selective Gold Plating on Contact Area  
 Gold Plating Thickness: (Au 1u", 3u", 6u", 15u", 30u", 50u")  
 100u" Min. Matte Tin Plated on Soldering Area  
 50u" Min. Nickel Plated Overall  
 Shell: Copper Alloy, 0.25mm Thickness

**Electrical:**

Voltage Rating: 125 V AC RMS  
 Current Rating: 1.5 Amp  
 Contact Resistance: 30mΩ Max.  
 Insulation Resistance: 500MΩ Min. @ 500 VDC  
 Dielectric Withstanding Resistance: 1000 VAC RMS 50Hz, 1 Min.

**Mechanical:**

Durability : 750 Cycles Min.

**Environmental:**

Storage Temperature : -40°C to +85°C  
 Operation Temperature: -40°C to +85°C

Reflow Soldering Temperature : 255°C to 265°C, 5-10 seconds

MJ5611 - X X X X X

No. of Positions	Positions Loaded	Insulator Material	Contact Plating	Packing Style
4,6,8	2,4,6,8	1 - PBT 2 - PA66 3 - PA46 4 - LCP	1 - 1μ" 2 - 3μ" 3 - 6μ" 4 - 15μ" 5 - 30μ"	1 - Tape & Reel 2 - Plastic Tray

GENERAL TOLERANCE		ANGLE TOLERANCE	
X.	±0.60	X.	±5°
.X	±0.38	.X	±3°
.XX	±0.25	.XX	±2°
DRAWING TYPE		CUSTOMER	
SCALE	1:1	SHEET	1 OF 1
DRAWING NO.	MJ5611- XXXXX		

PROJECTION	TITLE
mm	RJ45 SMT Jack, Right Angle, Unshielded, 8P8C, H=12.5mm
SHEET SIZE	A4
SERIES	SMT SERIES

**WAYCONN CO.,LTD**